

# **BOOSTXL-TLC2543 EVM User Guide**

The TLC2543-Q1 BoosterPack™ Plug-in Module (BOOSTXL-TLC2543) allows users to evaluate the functionality of Texas Instruments' TLC2543-Q1 SAR ADC. The TLC2543-Q1 is a 12-bit, 11-channel, automotive qualified SAR ADC. This user's guide describes both the hardware platform with an TLC2543-Q1 device and the graphical user interface (GUI) software used to configure the various modes of operation of this device.

## **Contents**

1	Introduction .....	2
2	BOOSTXL-TLC2543 EVM Overview .....	3
3	BOOSTXL-TLC2543 EVM Setup .....	5
4	BOOSTXL-TLC2543 EVM GUI Operation .....	13
5	Bill of Materials, Printed-Circuit Board Layout, and Schematics .....	17

## **List of Figures**

1	BOOSTXL-TLC2543 EVM Block Diagram .....	2
2	BOOSTXL-TLC2543EVM Top Level Overview .....	3
3	BOOSTXL-TLC2543 EVM GUI Installation .....	5
4	BOOSTXL-TLC2543 EVM Driver Installation .....	6
5	TM4C1294 LaunchPad™ Development Kit Stellaris Virtual Serial Port and ICDI Driver .....	7
6	TM4C1294 LaunchPad™ Development Kit Software Programming Setup .....	8
7	TM4C1294 LaunchPad™ Development Kit Selection in Configuration Tab .....	9
8	TM4C1294 LaunchPad™ Development Kit Programming Using LM Flash Programmer .....	10
9	TMC1294 LaunchPad™ Development Kit VIA BoosterPack™ Plug-in Module Driver .....	11
10	BOOSTXL-TLC2543 EVM stacked on TM4C1294 LaunchPad™ Development Kit .....	12
11	BOOSTXL-TLC2543 GUI Landing Page .....	13
12	AIN0 (Channel0) Voltage .....	14
13	Frequency Domain Analysis Page .....	15
14	BOOSTXL-TLC2543 Top Layer Routing .....	18
15	BOOSTXL-TLC2543 Ground Layer .....	19
16	BOOSTXL-TLC2543 Power Layer .....	20
17	BOOSTXL-TLC2543 Bottom Layer Routing .....	21
18	BOOSTXL-TLC2543 EVM Schematic Diagram .....	22

## **List of Tables**

1	Input Connector and Channel Configuration .....	3
2	Bill of Materials .....	17

## **Trademarks**

BoosterPack, LaunchPad are trademarks of Texas Instruments.  
 All other trademarks are the property of their respective owners.

## 1 Introduction

The BOOSTXL-TLC2543 is a fully-assembled evaluation platform designed to highlight the TLC2543-Q1 device features and its various modes of operations.

The BOOSTXL-TLC2543 EVM interfaces to the TM4C1294 LaunchPad™ Development Kit ([EK-TM4C1294XL](#)). The Tiva C Series TM4C1294 MCU on the TM4C1294 LaunchPad Development Kit communicates with the TLC2543-Q1 through its SPI interface and acts as a USB-to-PC GUI communication bridge.

---

**NOTE:** The BOOSTXL-TLC2543 requires an external master controller to evaluate the TLC2543-Q1.

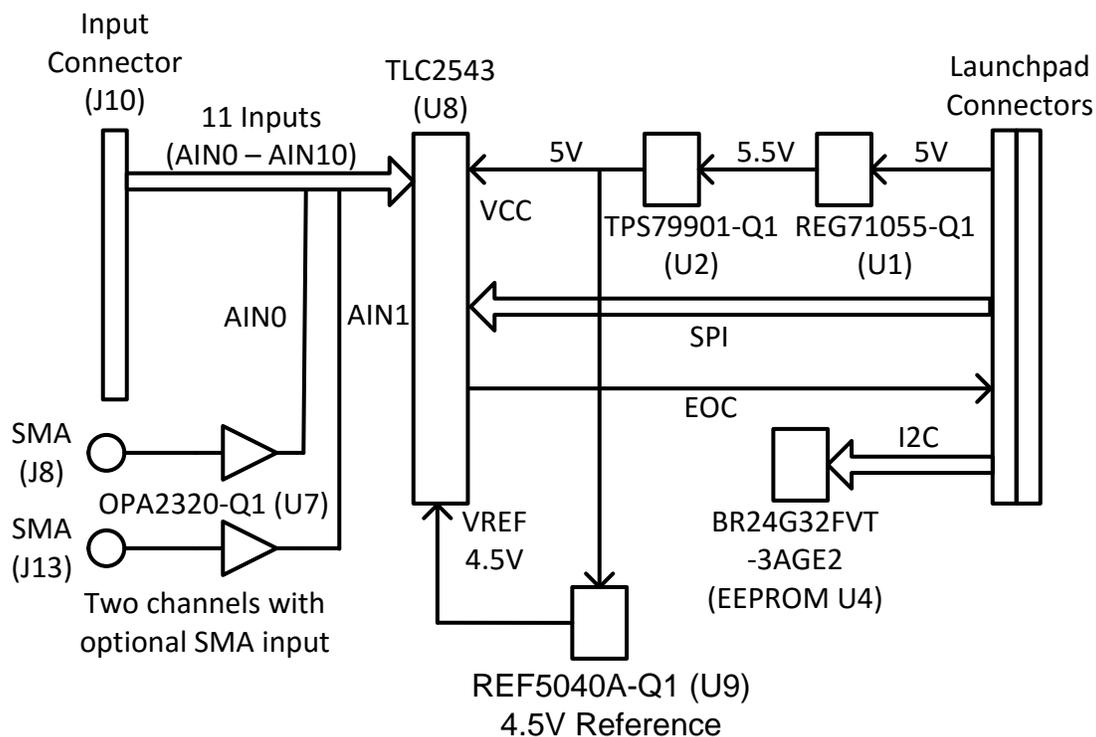
---

The TM4C1294 LaunchPad Development Kit is controlled by commands received from the BOOSTXL-TLC2543 EVM GUI, and the kit returns the data to the GUI for display and analysis. If the TM4C1294 LaunchPad Development Kit is not used, the BoosterPack™ Plug-in Module format of the BOOSTXL-TLC2543 board allows an alternative external host to communicate with the TLC2543-Q1.

The BOOSTXL-TLC2543 EVM incorporates all required circuitry and components with the following features:

- The TLC2543-Q1 12-bit, 11-channel, automotive qualified SAR ADC with SPI interface
- The REF5045A optional low power voltage reference to generate a 4.5-V reference for the TLC2543-Q1 VREF pin when using 5.0 V from TM4C1294 LaunchPad Development Kit
- The OPA2320 optional precision, low noise, dual operational amplifier to generate buffered input for the TLC2543-Q1 AIN0 and AIN1 pins
- The TPS79901 optional adjustable linear regulator to generate stable 5V output voltage to power the TLC2543-Q1 VCC pin when using the USB power from the TM4C1294 LaunchPad Development Kit
- SPI interface for communication and configuration of modes available on the TLC2543-Q1

Figure 1 shows the BOOSTXL-TLC2543 EVM architecture along with the key components and blocks listed in the features.



**Figure 1. BOOSTXL-TLC2543 EVM Block Diagram**

## 2 BOOSTXL-TLC2543 EVM Overview

Section 2 lists various onboard components that are used to interface analog input, digital interface, and provide power supply to BOOSTXL-TLC2543 EVM. Figure 2 shows a BOOSTXL-TLC2543 EVM overview.

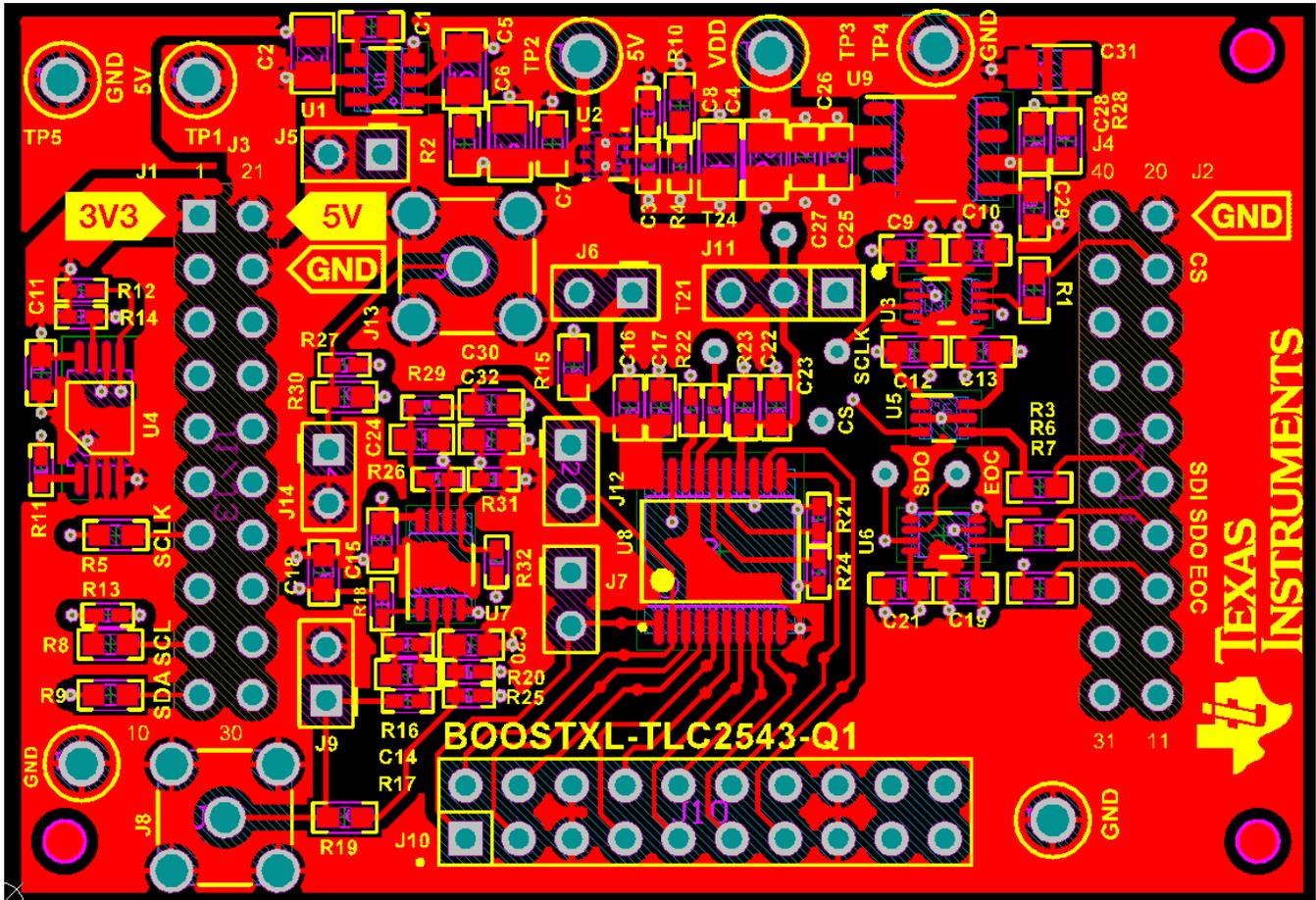


Figure 2. BOOSTXL-TLC2543EVM Top Level Overview

### 2.1 Connectors for Analog Input

The BOOSTXL-TLC2543 EVM is designed for easy interface-to-analog sources through a 100-mil header. Connector J10 allows analog source connectivity. Table 1 lists the analog input connector and input channel configuration.

Table 1. Input Connector and Channel Configuration

J10 Connector Pin	Description
J10:1	Analog input for channel 0 of ADC
J10:2	Analog input for channel 1 of ADC
J10:3	Analog input for channel 2 of ADC
J10:4	Analog input for channel 3 of ADC
J10:5 and J10:6	BoosterPack™ Plug-in Module ground
J10:7	Analog input for channel 4 of ADC
J10:8	Analog input for channel 5 of ADC
J10:9	Analog input for channel 6 of ADC
J10:10	Analog input for channel 7 of ADC
J10:11	Analog input for channel 8 of ADC

**Table 1. Input Connector and Channel Configuration (continued)**

J10 Connector Pin	Description
J10:12	Analog input for channel 9 of ADC
J10:13	Analog input for channel 10 of ADC
J10:15 and J10:16	BoosterPack™ Plug-in Module ground
J10:14, 17, 18, 19, 20	No Connection

The analog input range is from GND to +VREF. A maximum of 11 single-ended inputs may be applied to J10 using pins J10:1 to J10:4 and J10:7 to J10:13.

The user can configure the input to channel 0 to use the OPA2320 buffer through a 100-Ω resistor with an 1000-pF capacitor to GND. Jumper J7 can be placed on pins 1-2 to select this unity gain buffer configuration of the OPA2320. In this case, the channel 0 input is provided through the SMA connector J8. The user can also place Jumper J12 on pins 1-2 to create a similar configuration for a channel 1 input provided through the SMA connector J13.

## 2.2 Voltage Reference

The BOOSTXL-TLC2543 EVM has two sources for the reference voltage. Jumper J11 can select the VREF voltage from either the REF5045A (U9) or from 5-V VCC. The EVM is factory-configured for use with the REF5045A 4.5-V reference (J11 pins 2-3).

## 2.3 Digital Interface

As noted in [Section 1](#), the BOOSTXL-TLC2543 EVM interfaces with the TM4C1294 LaunchPad Development Kit, which in turn communicates with the computer over USB. The two devices on the booster pack that the TM4C1294 communicates with are the TLC2543-Q1 ADC (over SPI) and the EEPROM (over I<sup>2</sup>C). The EEPROM comes preprogrammed with the information required to configure and initialize the BOOSTXL-TLC2543 EVM platform every time on power up.

## 2.4 BOOSTXL-TLC2543 Digital I/O Interface

The BOOSTXL-TLC2543 EVM supports the SPI digital interface and functional modes as detailed in the [TLC2543-Q1](#) data sheet. The TM4C1294 LaunchPad Development Kit is operating at a 3.3-V logic level and is connected to the 5-V digital I/O lines of the ADC through level shifters (SN74LVC1T45QDCURQ1 and SN74LVC2T45QDCURQ1).

## 2.5 Power Supply

The device supports a single power supply with a wide range of operation. The VCC can operate from 2.7 V to 5 V. The available onboard TPS79901 adjustable voltage regulator is configured to supply 5 V to the TLC2543-Q1 VCC pin on the BOOSTXL-TLC2543 EVM.

### 3 BOOSTXL-TLC2543 EVM Setup

#### 3.1 BOOSTXL-TLC2543 EVM Graphical User Interface Software Installation

The following steps describe the BOOSTXL-TLC2543 EVM GUI software installation:

1. Download the latest version of the EVM graphical user interface (GUI) installer from the [Tools and Software](#) folder of the device, and run the GUI installer to install the EVM GUI software on your windows PC.
2. Accept the *License Agreements* and follow the on-screen instructions to complete the installation (see [Figure 3](#)).

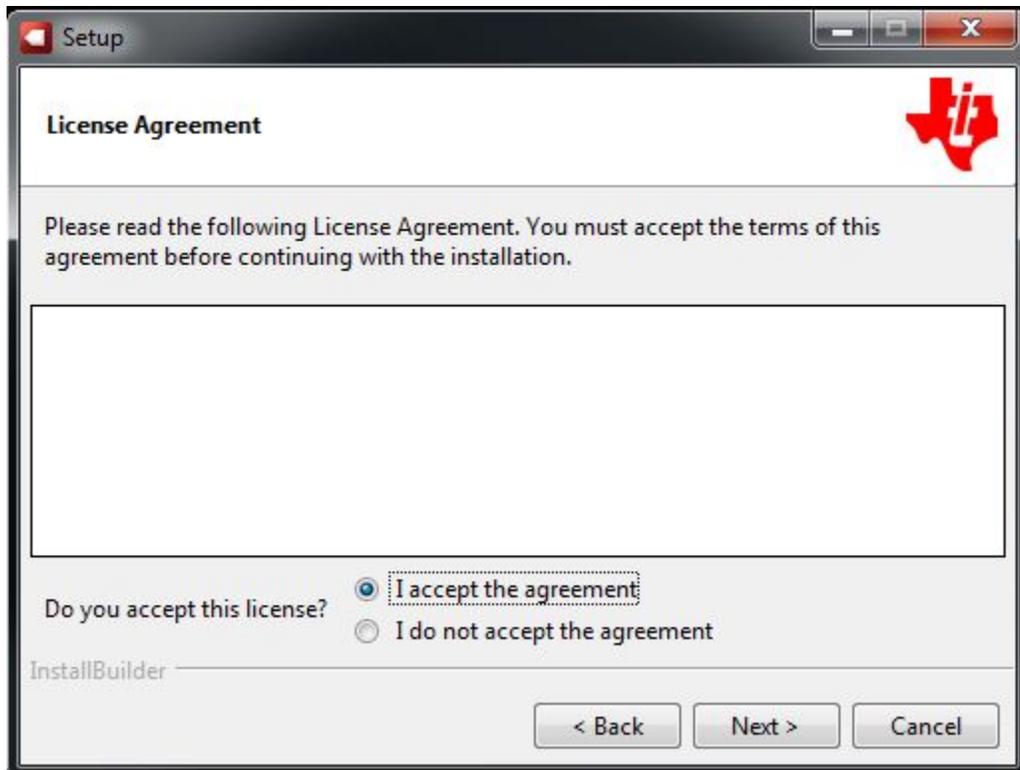


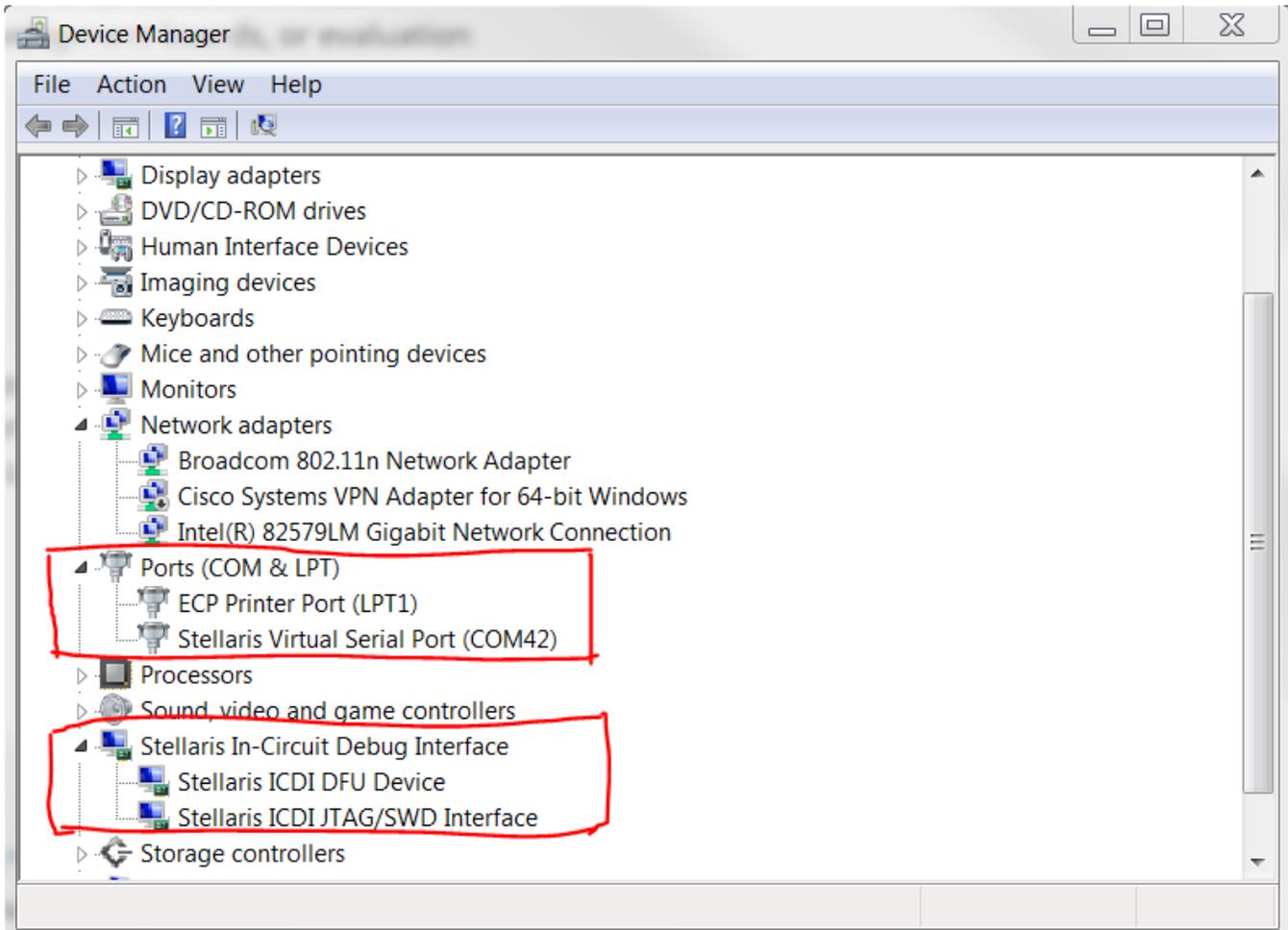
Figure 3. BOOSTXL-TLC2543 EVM GUI Installation

3. Click the *Next* button when the *Device Driver Installation Wizard* prompt appears on the screen to start the installation process (see [Figure 4](#)). Click the *Finish* button when the install is complete.



**Figure 4. BOOSTXL-TLC2543 EVM Driver Installation**

4. Open the computer's "Device Manager". You must be able to see the "Stellaris Virtual Serial Port" and "Stellaris In-Circuit Debug Interface" as shown in [Figure 5](#).

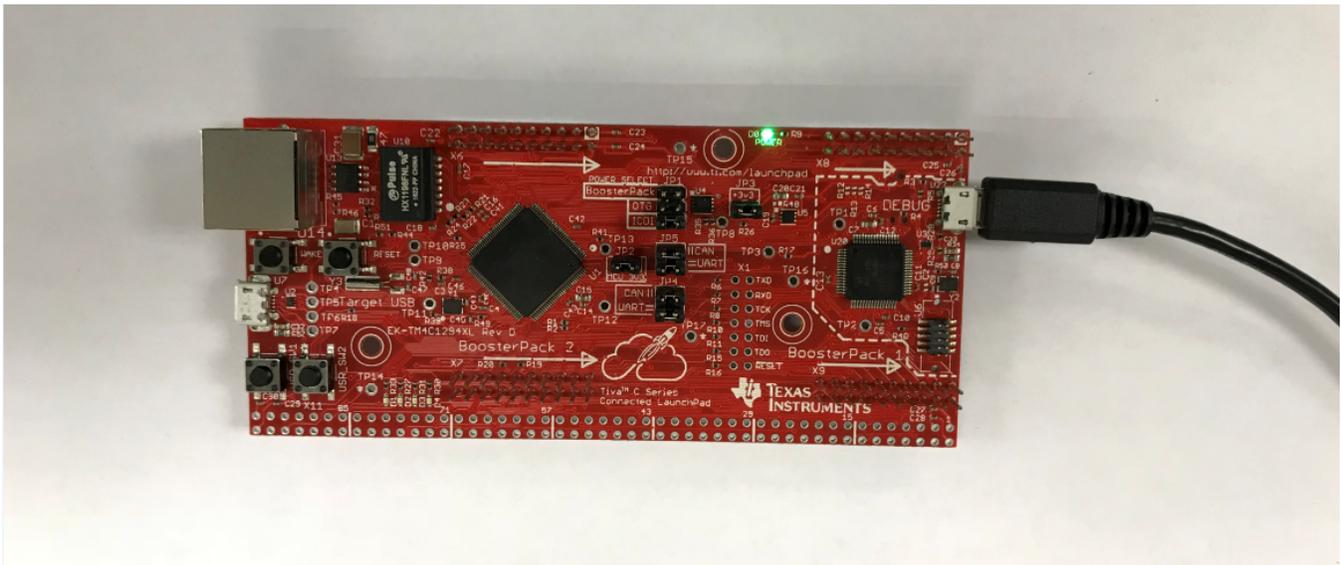


**Figure 5. TM4C1294 LaunchPad™ Development Kit Stellaris Virtual Serial Port and ICDI Driver**

### 3.2 LM Flash Programmer for TM4C1294 LaunchPad™ Development Kit Software Programming

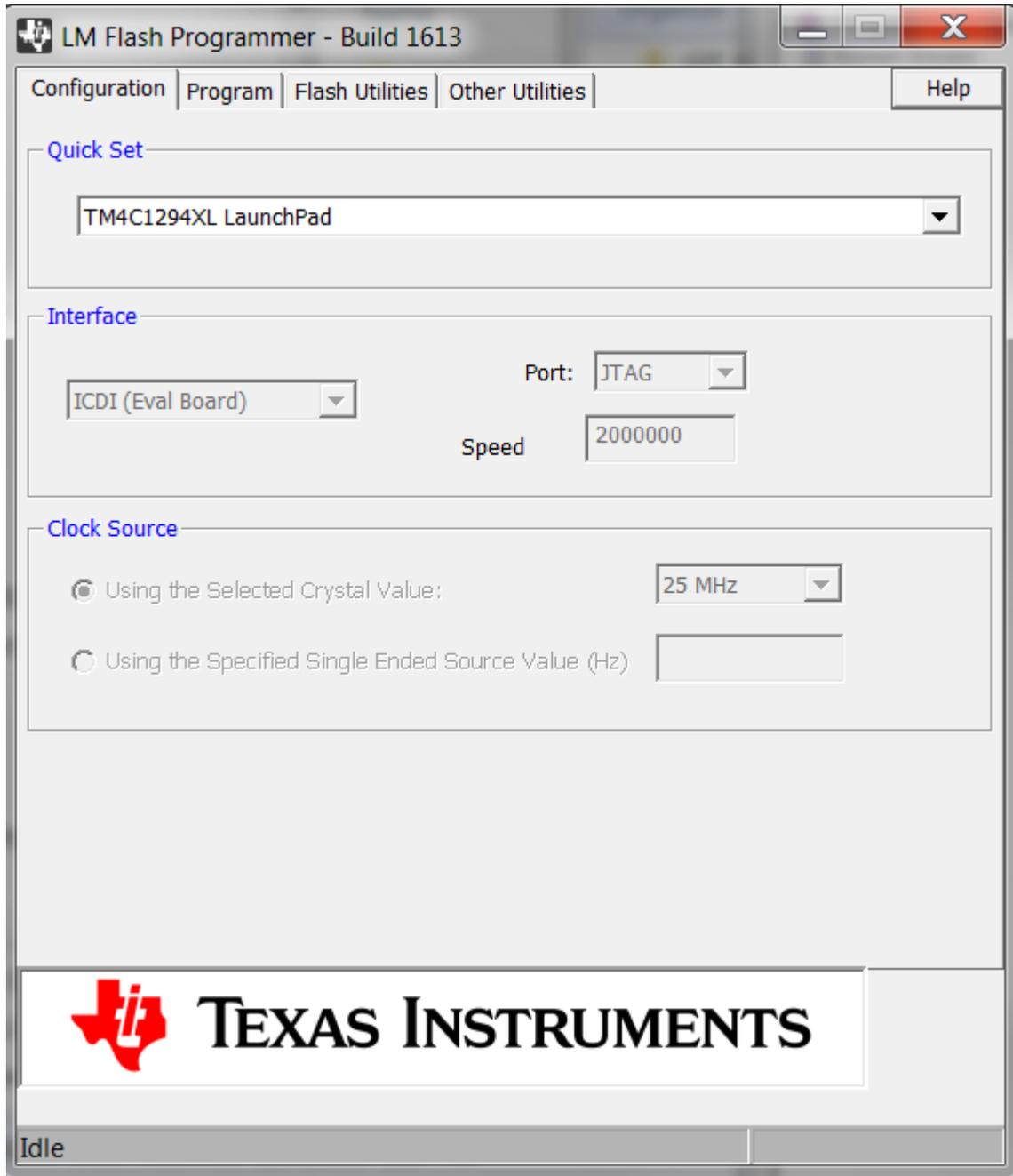
The TM4C1294 LaunchPad Development Kit ships with a default firmware program flashed on its memory. When a TM4C1294 LaunchPad Development Kit is connected to the PC for the first time, its firmware needs to be updated for communications with the BOOSTXL-TLC2543 EVM. The following steps describe the programming of this firmware on the flash memory:

1. Download the latest version of [LM Flash Programmer](#). The LM Flash Programmer is also included as part of the BOOSTXL-TLC2543 EVM GUI installation in the following folder: C:\Program Files (x86)\Texas Instruments\TLC2543\Firmware
2. Make sure the power select JP1 jumper on the TM4C1294 LaunchPad Development Kit is on ICDI. Connect the *Debug USB port* on the TM4C1294 LaunchPad Development Kit to the PC with a micro USB cable as shown in [Figure 6](#). This must light the green power LED D0 on the TM4C1294 LaunchPad Development Kit.



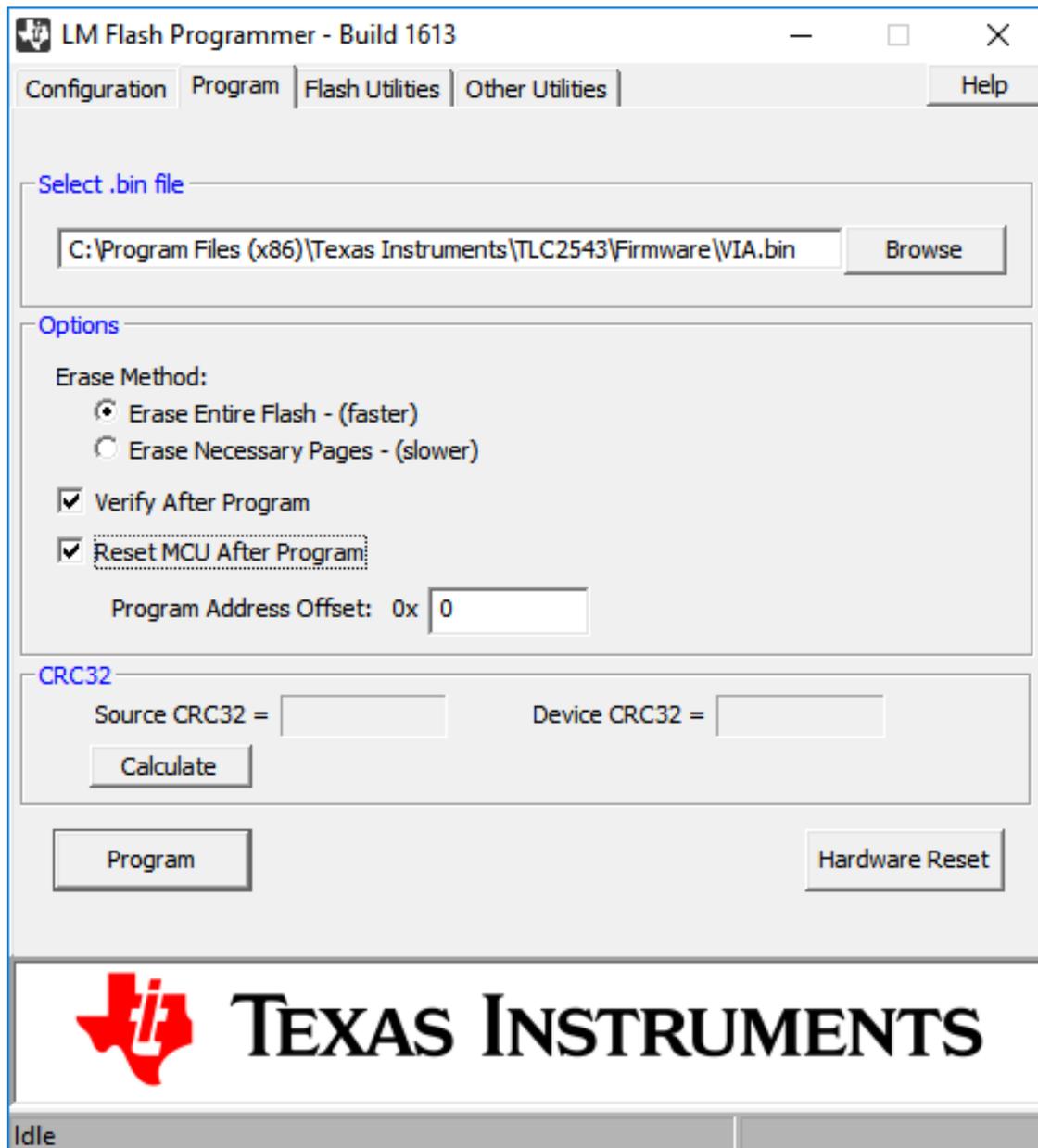
**Figure 6. TM4C1294 LaunchPad™ Development Kit Software Programming Setup**

3. Launch the LM Flash Programmer. In the Configuration tab select *TM4C1294XL LaunchPad* from the drop-down menu as shown in [Figure 7](#).



**Figure 7. TM4C1294 LaunchPad™ Development Kit Selection in Configuration Tab**

4. Program the TM4C1294 with the BOOSTXL-TLC2543 EVM firmware from the Program tab as shown in Figure 8.



**Figure 8. TM4C1294 LaunchPad™ Development Kit Programming Using LM Flash Programmer**

5. Disconnect the micro USB cable from the TM4C1294 LaunchPad Development Kit debug port after programming and verification is successful. Switch the power select JP1 jumper position from ICDI to the OTG location.

### 3.3 BOOSTXL-TLC2543 EVM Stack Up

The following steps are the instructions to set up the BOOSTXL-TLC2543 EVM for evaluation:

1. Stack the BOOSTXL-TLC2543 EVM on the TM4C1294 LaunchPad Development Kit. Make sure the 20-pin connector (J1, J3) on BOOSTXL-TLC2543 EVM is mapped against connector X6 and connector (J4, J2), and that the BOOSTXL-TLC2543 EVM is mapped against connector X7 on the TM4C1294 LaunchPad Development Kit. Pin 1 of BOOSTXL-TLC2543 EVM must align with pin 1 of connector X6 on the TM4C1294 LaunchPad Development Kit.
2. Position the power select JP1 jumper on the TM4C1294 LaunchPad Development Kit on pins that correspond to the OTG.
3. Connect the TM4C1294 LaunchPad Development Kit USB port U7 to the PC with the micro USB cable. This must light the green power LED D0 on the TM4C1294 Development Kit
4. Open computer's "Device Manager". You must see under ports "VIA USB BoosterPack" and "VIA USB BoosterPack Console" as shown in [Figure 9](#)

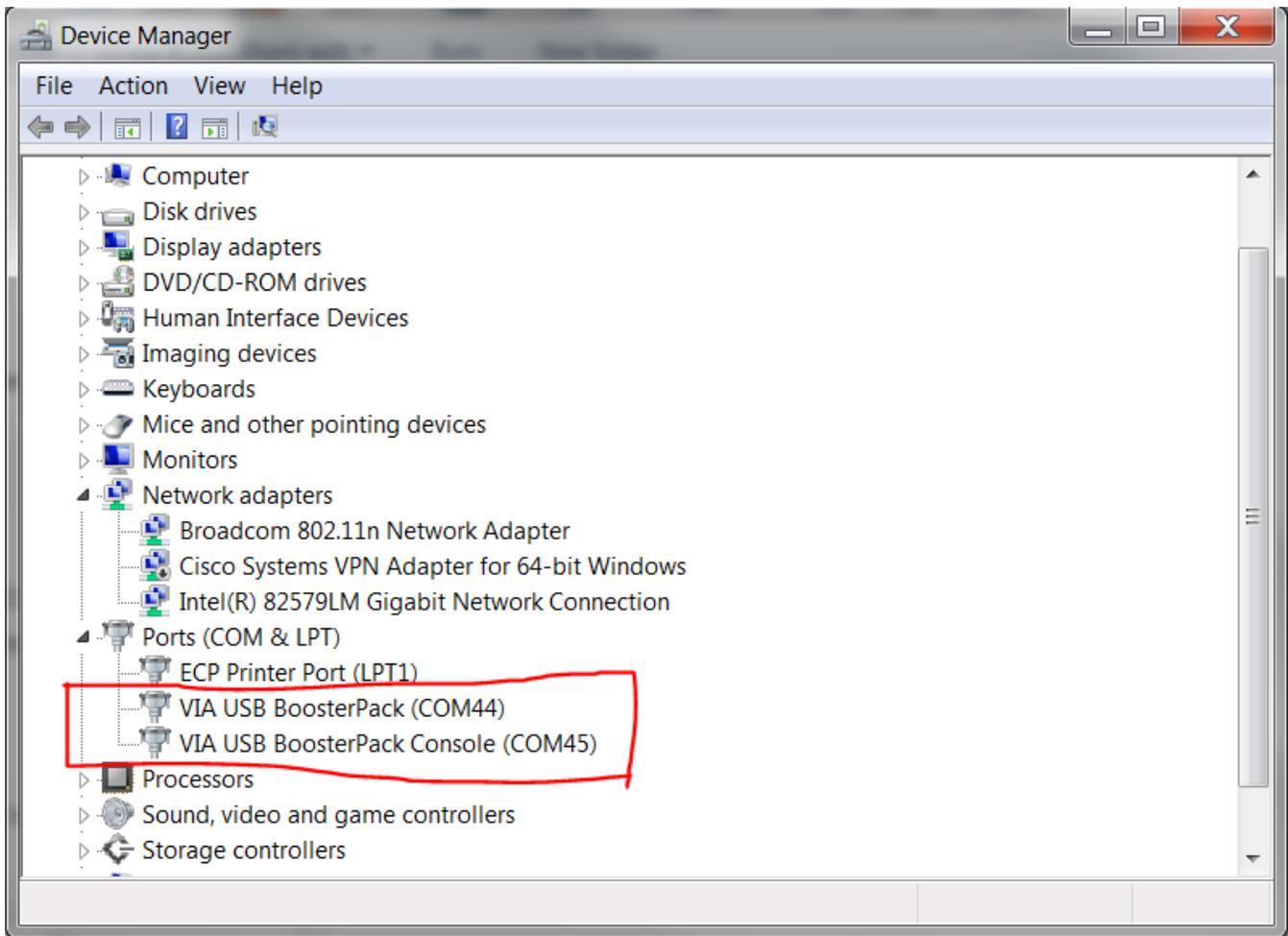
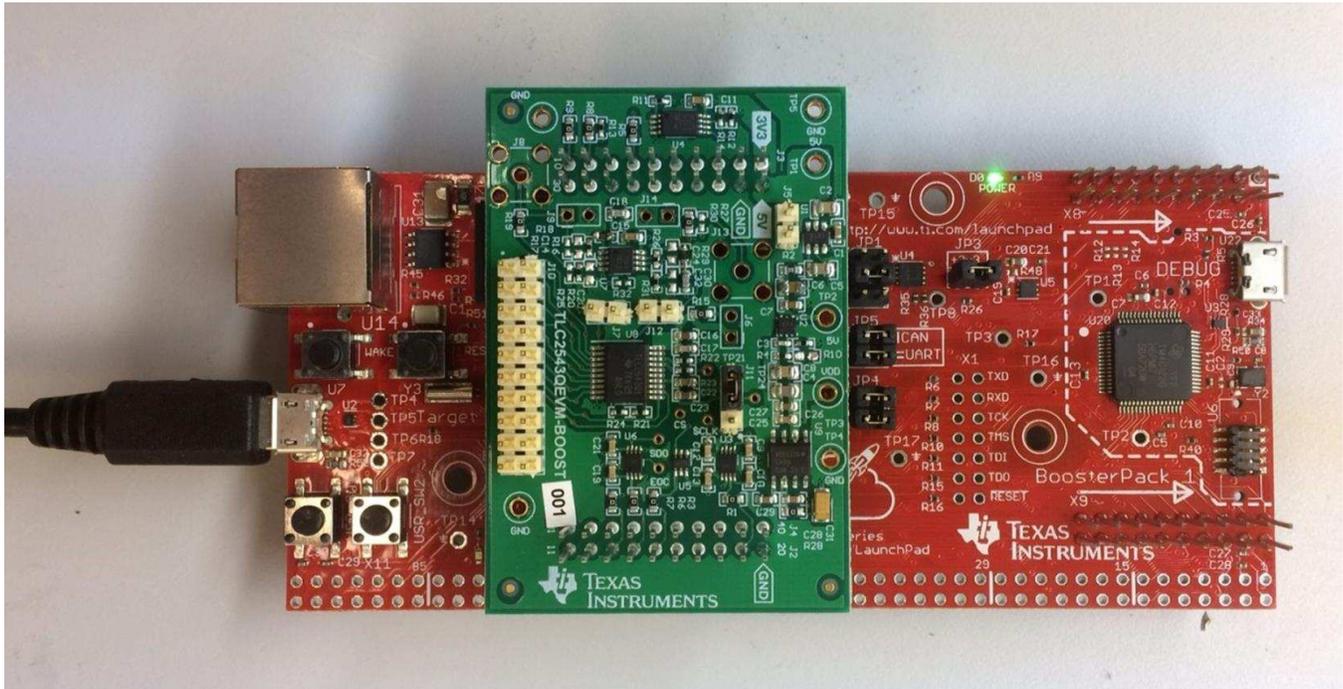


Figure 9. TMC1294 LaunchPad™ Development Kit VIA BoosterPack™ Plug-in Module Driver

5. **Figure 10** shows the assembled BOOSTXL-TLC2543 EVM and TM4C1294 LaunchPad Development Kit configuration.



**Figure 10. BOOSTXL-TLC2543 EVM stacked on TM4C1294 LaunchPad™ Development Kit**

## 4 BOOSTXL-TLC2543 EVM GUI Operation

### 4.1 Description

Figure 11 shows the landing page of the BOOSTXL-TLC2543 EVM GUI. This page provides a high-level overview of the TLC2543-Q1 device. The left corner shows the tabs required to navigate to the BOOSTXL-TLC2543 EVM GUI *Home* and *Analysis* pages. When the TM4C1294 LaunchPad Development Kit with the stacked BOOSTXL-TLC254 EVM is connected to the PC with the micro USB cable, the GUI reads the onboard EEPROM to detect the BoosterPack Plug-in Module. Once the BoosterPack Plug-in Module is detected and connected, the GUI indicates this status at the bottom left corner of the GUI.

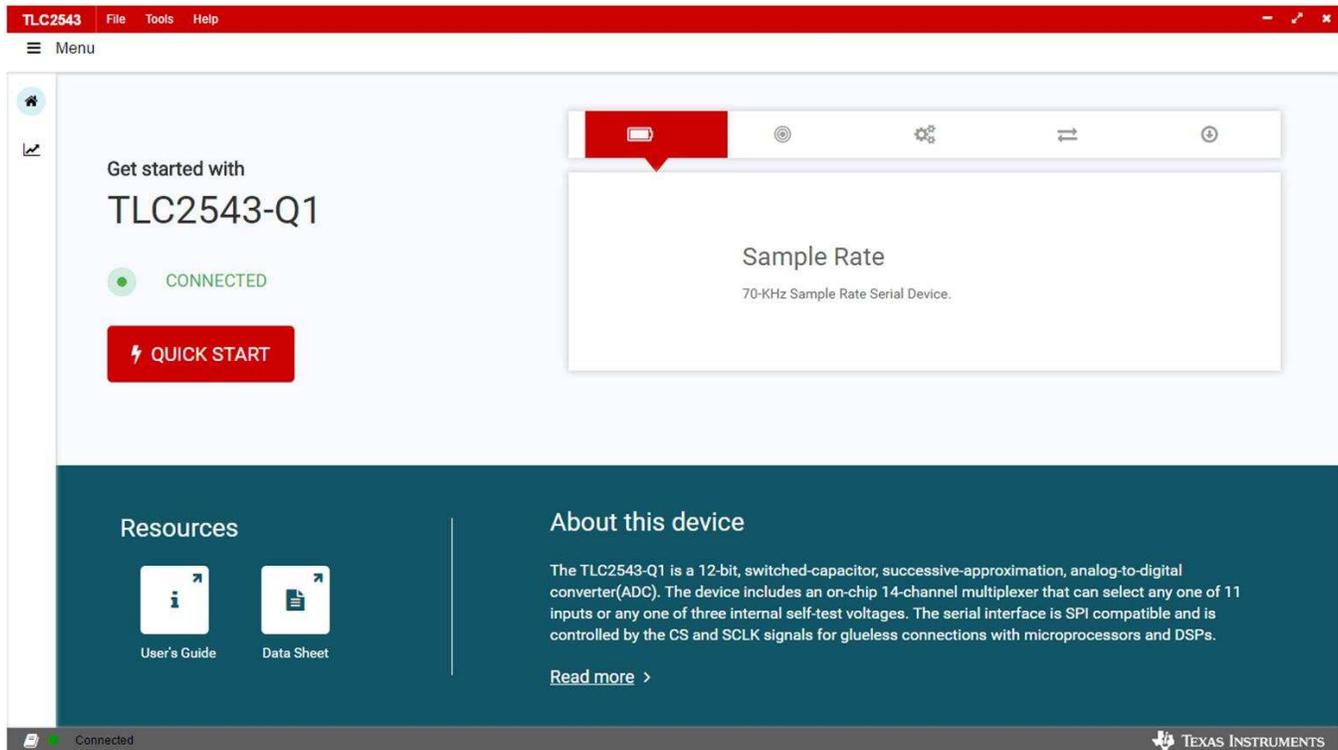


Figure 11. BOOSTXL-TLC2543 GUI Landing Page

## 4.2 Time Domain Analysis

Go to *Analysis* page, and select the *Time Domain* Analysis. Time Domain Analysis displays the acquired data versus time for the selected channel as shown in [Figure 12](#). Note default reference voltage for ADC measurement *REF Volt (V)* is set as 4.5 V.

### 4.2.1 Measure AIN0 (Channel0) Voltage

This section describes the steps involved in selecting and measuring AIN0 (Channel0) voltage:

1. Make sure following shunt is in place on the BOOSTXL-TLC2543 EVM: J11 between 2 and 3 (select VREF = 4.5 V)
2. Connect J10.1 to J1.1 (3.3 V) by a jumper wire.
3. Select "Samples" as 4096, set "SCLK" as 1000 (KHz), and set "Sample Rate" as 10 (KHz).
4. Make sure "Selected Channel" is Channel0 as shown in [Figure 12](#) below.
5. Press "Collect".
6. Make sure the Min Code, Max Code, Min Volt (V), and Max Volt (V) read outs are shown. See [Figure 12](#) for an example.



Figure 12. AIN0 (Channel0) Voltage

### 4.3 Frequency Domain Analysis

The *Frequency Domain* page in the GUI performs the fast fourier transform (FFT) of the captured data and shows the resulting frequency domain plots of the selected channel of TLC2543-Q1. This page also calculates key ADC dynamic performance parameters, such as signal-to-noise ratio (SNR), total harmonic distortion (THD), signal-to-noise and distortion ratio (SINAD), spurious-free dynamic range (SFDR), and effective number of bits (ENOB). [Figure 13](#) shows the Frequency Domain analysis display for a 2-kHz sinusoidal input generated by [PSIEVM](#).

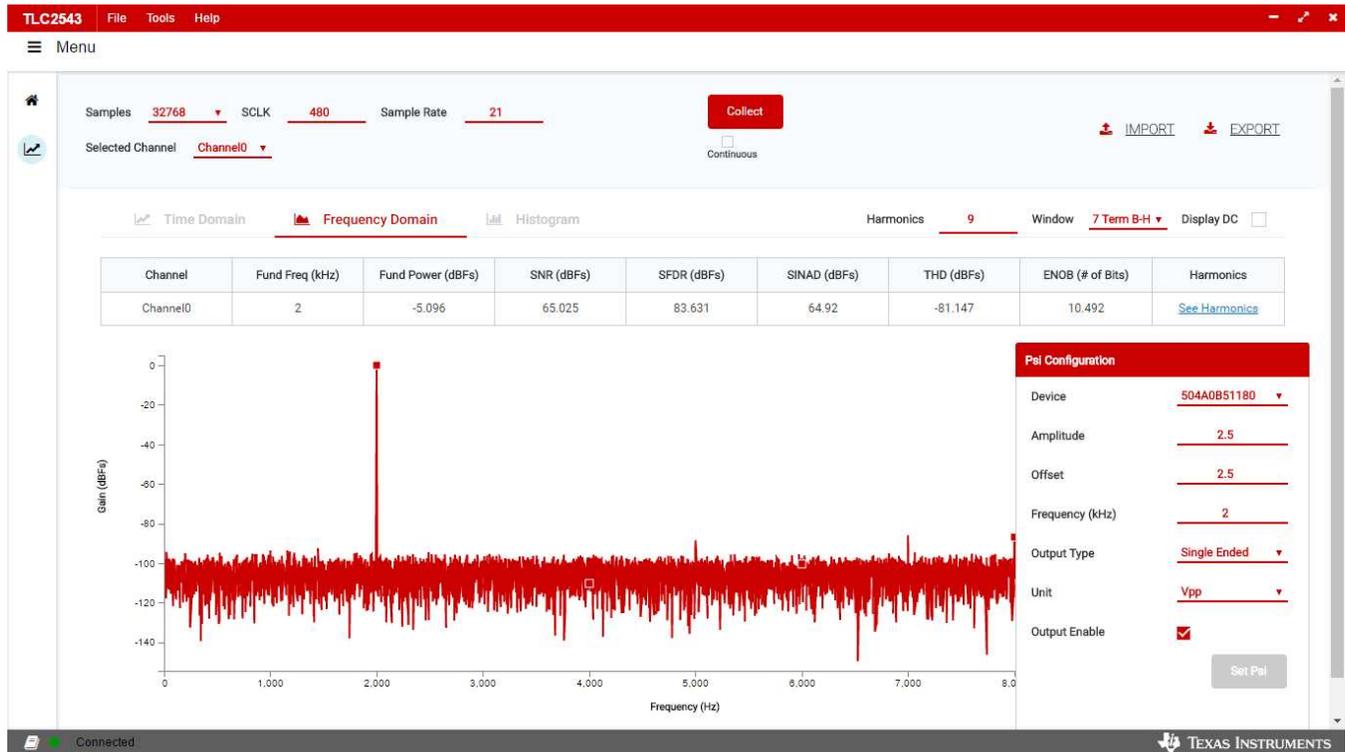


Figure 13. Frequency Domain Analysis Page

### 4.3.1 FFT Analysis Settings and Controls

**Sample Rate** - This field indicates the sampling frequency of the ADC data (kHz)

**Samples** - The FFT requires a time domain record with a number of samples that is a power of 2. The Samples drop-down menu provides a list of values that satisfy this requirement.

**Fund Freq (kHz)** - This field displays the frequency of the largest amplitude input signal computed from the FFT data, typically the fundamental frequency.

**Window** - The window function is a mathematical function that reduces the signal to zero at the end points of the data block.

In applications where coherent sampling cannot be achieved, a window-weighting function can be applied to the data to minimize spectral leakage. The following options are available:

- Rectangular
- Hamming
- Hann
- Blackman
- 7-Term Blackman-Harris

For a more thorough discussion of windowing, refer to IEEE1241-2000

**Harmonics** - This field sets the number of harmonics that are included in the FFT performance calculations.

## 4.4 Histogram Analysis

The *Histogram Analysis* page creates a histogram of the captured channel data and displays it. A histogram is merely a count of the number of times a code has occurred in a particular data set. The following parameters of the captured data set are displayed:

- The **Std Dev [ $\sigma$ ]** displays the standard deviation of the data set. This value is equivalent to the RMS noise of the signal when analyzing a dc data set.
- The **Mean** displays the average value of the data set.
- The **Median** displays the median value of the data set.
- The **Code Spread** displays the peak-to-peak spread of the codes in the data set; for a dc data set, this range would be the peak-to-peak noise.

## 5 Bill of Materials, Printed-Circuit Board Layout, and Schematics

This section contains the BOOSTXL-TLC2543 EVM bill of materials (BOM), printed-circuit board (PCB) layout, and schematics.

### 5.1 Bill of Materials

Table 2 lists the bill of materials (BOM) for the BOOSTXL-TLC2543 EVM.

**Table 2. Bill of Materials**

Designator	Quantity	Description	Manufacturer Part Number	Manufacturer
PCB	1	Printed Circuit Board	DC012	Any
C1	1	CAP, CERM, 0.22 $\mu$ F, 25 V, +/- 5%, X7R, 0603	C0603C224J3RAC7867	Kemet
C2, C4, C5	3	CAP, CERM, 2.2 $\mu$ F, 16 V, +/- 10%, X7R, 0805	C0805C225K4RACTU	Kemet
C3	1	CAP, CERM, 180 pF, 50 V, +/- 1%, C0G/NP0, 0402	04025A181FAT2A	AVX
C6	1	CAP, CERM, 10 $\mu$ F, 16 V, +/- 20%, X5R, 0805	0805YD106MAT2A	AVX
C7, C16, C23, C27, C28, C29	6	CAP, CERM, 1 $\mu$ F, 25 V, +/- 10%, X7R, 0603	C0603C105K3RACTU	Kemet
C9, C10, C12, C13, C17, C19, C21	7	CAP, CERM, 0.01 $\mu$ F, 16 V, +/- 10%, X7R, 0603	GRM188R71C103KA01D	MuRata
C11, C15	2	CAP, CERM, 0.1 $\mu$ F, 16 V, +/- 10%, X7R, 0603	GRM188R71C104KA01D	MuRata
C18, C30	2	CAP, CERM, 1000 pF, 50 V, +/- 5%, C0G/NP0, 0603	C0603C102J5GACTU	Kemet
C22, C25	2	CAP, CERM, 0.1 $\mu$ F, 25 V, +/- 10%, X5R, 0603	06033D104KAT2A	AVX
C26	1	CAP, CERM, 10 $\mu$ F, 25 V, +/- 10%, X5R, 0805	C2012X5R1E106K125AB	TDK
C31	1	CAP, TA, 10 $\mu$ F, 10 V, +/- 20%, 3 ohm, SMD	TAJA106M010RNJ	AVX
J1/J3, J2/J4	2	Receptacle, 2.54mm, 10x2, Tin, TH	SSQ-110-03-T-D	Samtec
J5, J7, J12	3	Header, 100mil, 2x1, Tin, TH	PEC02SAAN	Sullins Connector Solutions
J10	1	Header, 100mil, 10x2, Gold, TH	TSW-110-07-G-D	Samtec
J11	1	Header, 100mil, 3x1, Tin, TH	PEC03SAAN	Sullins Connector Solutions
R1, R3, R5, R6, R7, R8, R9, R15, R19, R28, R30	11	RES, 0, 5%, 0.1 W, 0603	CRCW06030000Z0EA	Vishay-Dale
R2	1	RES, 10.0, 1%, 0.1 W, 0603	RC0603FR-0710RL	Yageo America
R4	1	RES, 100 k, 0.1%, 0.063 W, 0402	RG1005P-104-B-T5	Susumu Co Ltd
R10	1	RES, 31.6 k, 1%, 0.063 W, 0402	CRCW040231K6FKED	Vishay-Dale
R11, R14	2	RES, 10.0 k, 1%, 0.063 W, 0402	CRCW040210K0FKED	Vishay-Dale
R12, R13	2	RES, 1.00 k, 1%, 0.0625 W, 0402	RC0402FR-071KL	Yageo America
R16, R26	2	RES, 100 k, 5%, 0.063 W, 0402	CRCW0402100KJNED	Vishay-Dale
R18, R29	2	RES, 100, 1%, 0.063 W, 0402	CRCW0402100RFKED	Vishay-Dale
R20, R31	2	RES, 1.0 M, 5%, 0.063 W, 0402	CRCW04021M00JNED	Vishay-Dale
R21, R22, R23, R24	4	RES, 49.9, 1%, 0.063 W, 0402	RC0402FR-0749R9L	Yageo America
SH-J1	1	Shunt, 100mil, Gold plated, Black	382811-6	AMP
TP4, TP5, TP6, TP7	4	Test Point, Miniature, Black, TH	5001	Keystone
U1	1	5.5 V, Buck-Boost Charge Pump Regulator, 60 mA, 3 to 5.5 V Input, -40 to 85 degC, 6-pin SOT23 (DCC6), Green (RoHS & no Sb/Br)	REG71055IDDCRQ1	Texas Instruments
U2	1	Single Output High PSRR LDO, 200 mA, Adjustable 1.2 to 6.5 V Output, 2.7 to 6.5 V Input, with Low IQ, 6-pin SON (DRV), -40 to 125 degC, Green (RoHS & no Sb/Br)	TPS79901QDRVRQ1	Texas Instruments
U3, U6	2	Automotive Catalog Dual-Bit Dual Supply Transceiver with Configurable Voltage Translation, DCU0008A	SN74LVC2T45QDCURQ1	Texas Instruments
U4	1	I2C BUS EEPROM (2-Wire), TSSOP-B8	BR24G32FVT-3AGE2	Rohm
U5	1	Automotive Catalog Single-Bit Dual-Supply Bus Transceiver with Configurable Voltage Translation and, DCK0006A	SN74LVC1T45QDCKRQ1	Texas Instruments
U7	1	Automotive, Precision, 20MHz, 0.9pA Ib, RRIO, CMOS Operational Amplifier, DGK0008A (VSSOP-8)	OPA2320AQDGKRQ1	Texas Instruments

Table 2. Bill of Materials (continued)

Designator	Quantity	Description	Manufacturer Part Number	Manufacturer
U8	1	Automotive 12-Bit Analog-to-Digital Converter With Serial Control and 11 Analog Inputs, DB0020A (SSOP-20)	TLC2543IDBRQ1	Texas Instruments
U9	1	Automotive Catalog, Low Noise, Very Low Drift, Precision Voltage Reference, -40 to125 degC, 8-pin SOIC (D), Green (RoHS & no Sb/Br)	REF5045AQDRQ1	Texas Instruments
C8, C14, C20, C24, C32	0	CAP, CERM, 0.01 µF, 16 V, +/- 10%, X7R, 0603	GRM188R71C103KA01D	MuRata
J6, J9, J14	0	Header, 100mil, 2x1, Tin, TH	PEC02SAAN	Sullins Connector Solutions
J8, J13	0	SMA Straight PCB Socket Die Cast, 50 Ohm, TH	5-1814832-1	TE Connectivity
R17, R27	0	RES, 1.0 k, 5%, 0.063 W, 0402	CRCW04021K00JNED	Vishay-Dale
R25, R32	0	RES, 330 k, 5%, 0.063 W, 0402	CRCW0402330KJNED	Vishay-Dale
TP1, TP2, TP3, TP4, TP5, TP6, TP7	0	Test Point, Multipurpose, Black, TH	5011	Keystone

## 5.2 PCB Layout

Figure 14 to Figure 17 show the EVM PCB layout.

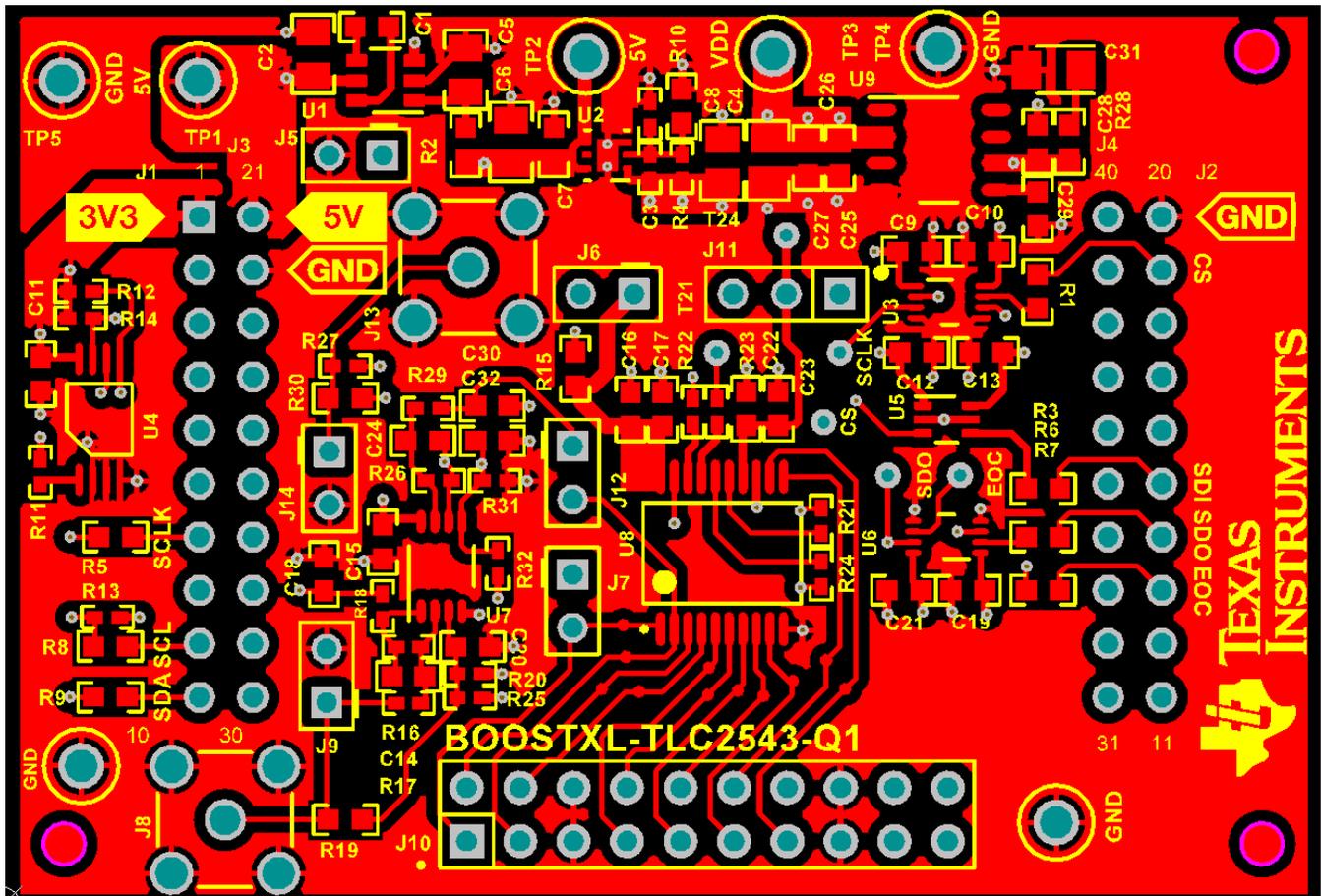


Figure 14. BOOSTXL-TLC2543 Top Layer Routing

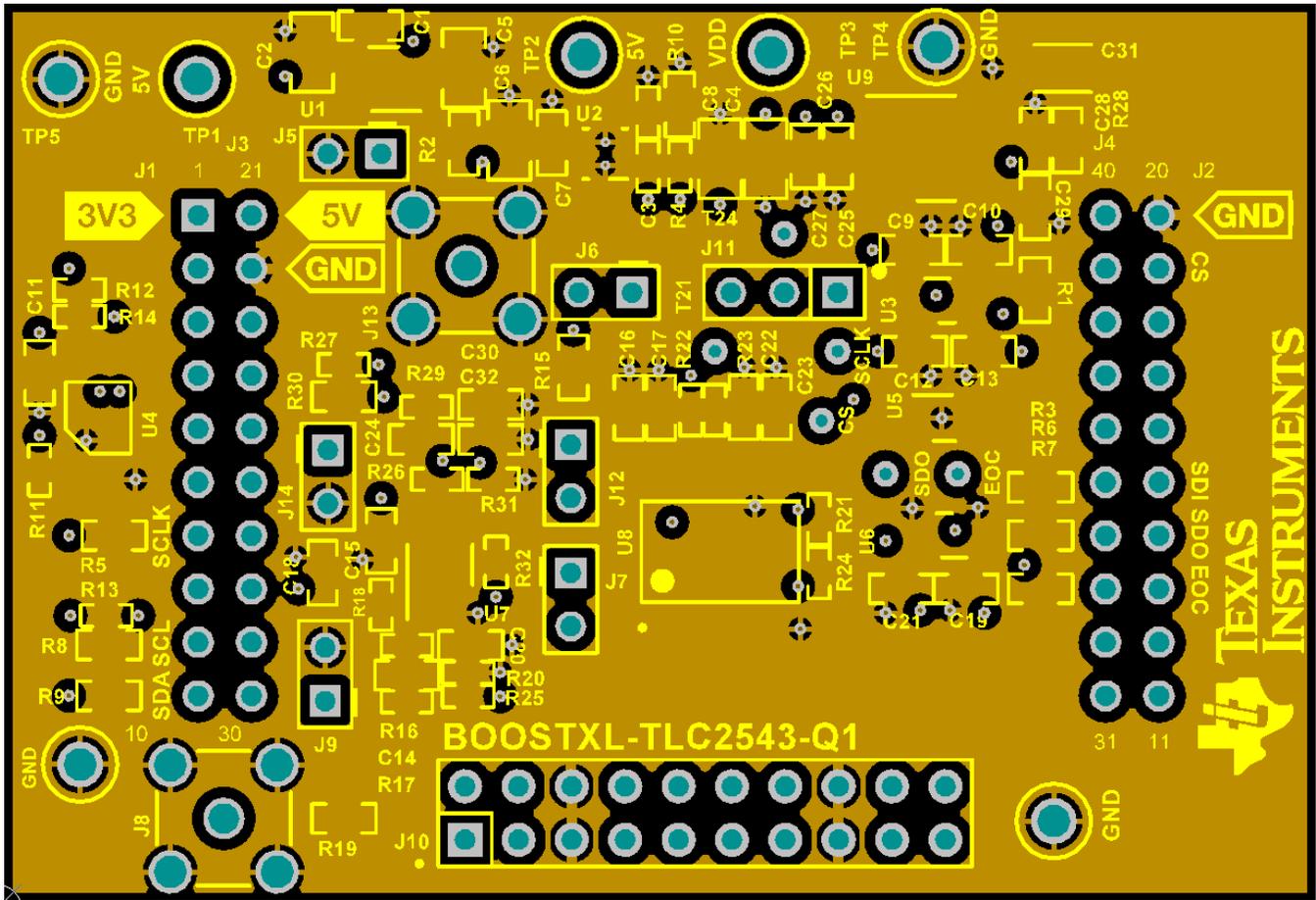


Figure 15. BOOSTXL-TLC2543 Ground Layer

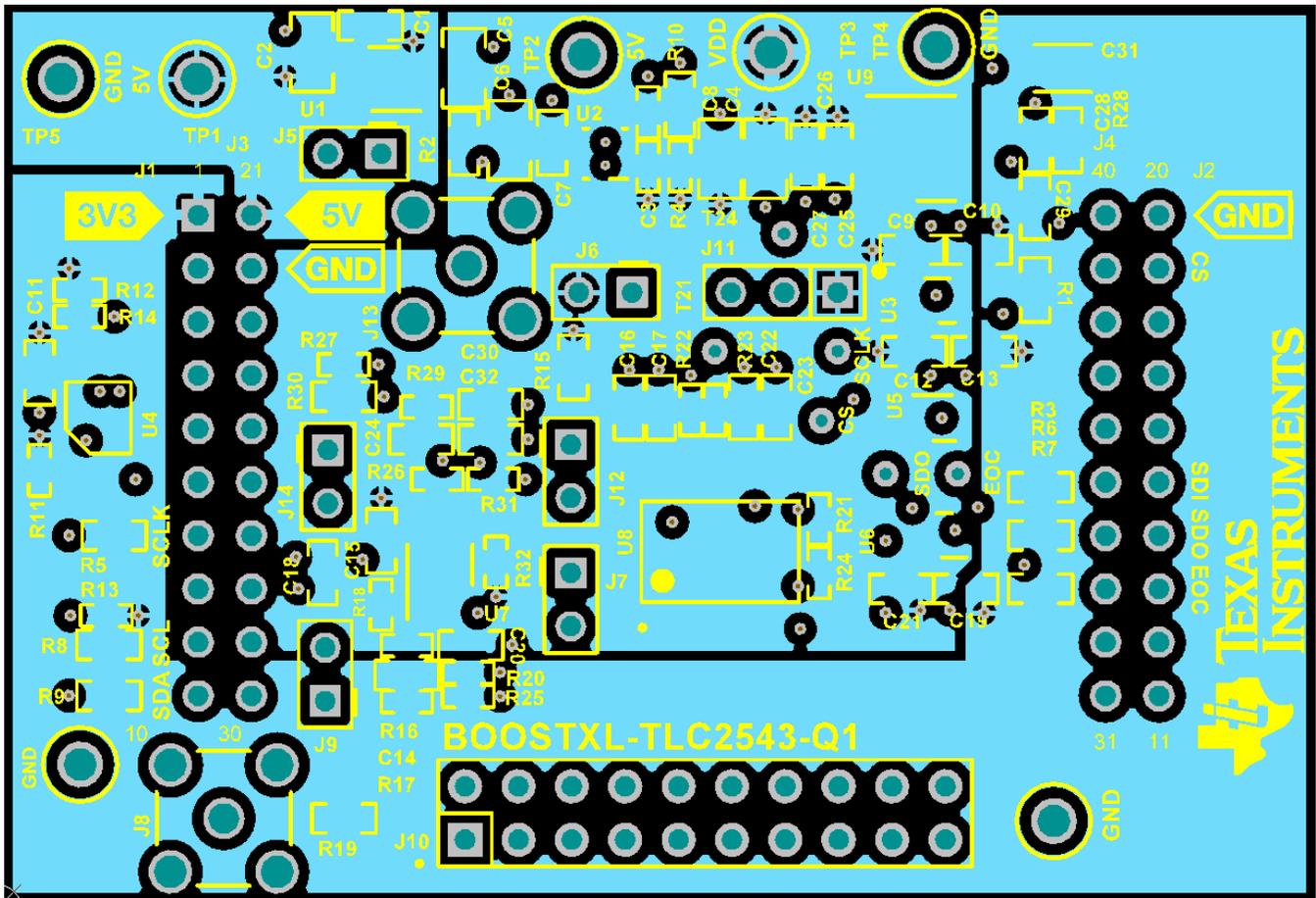


Figure 16. BOOSTXL-TLC2543 Power Layer

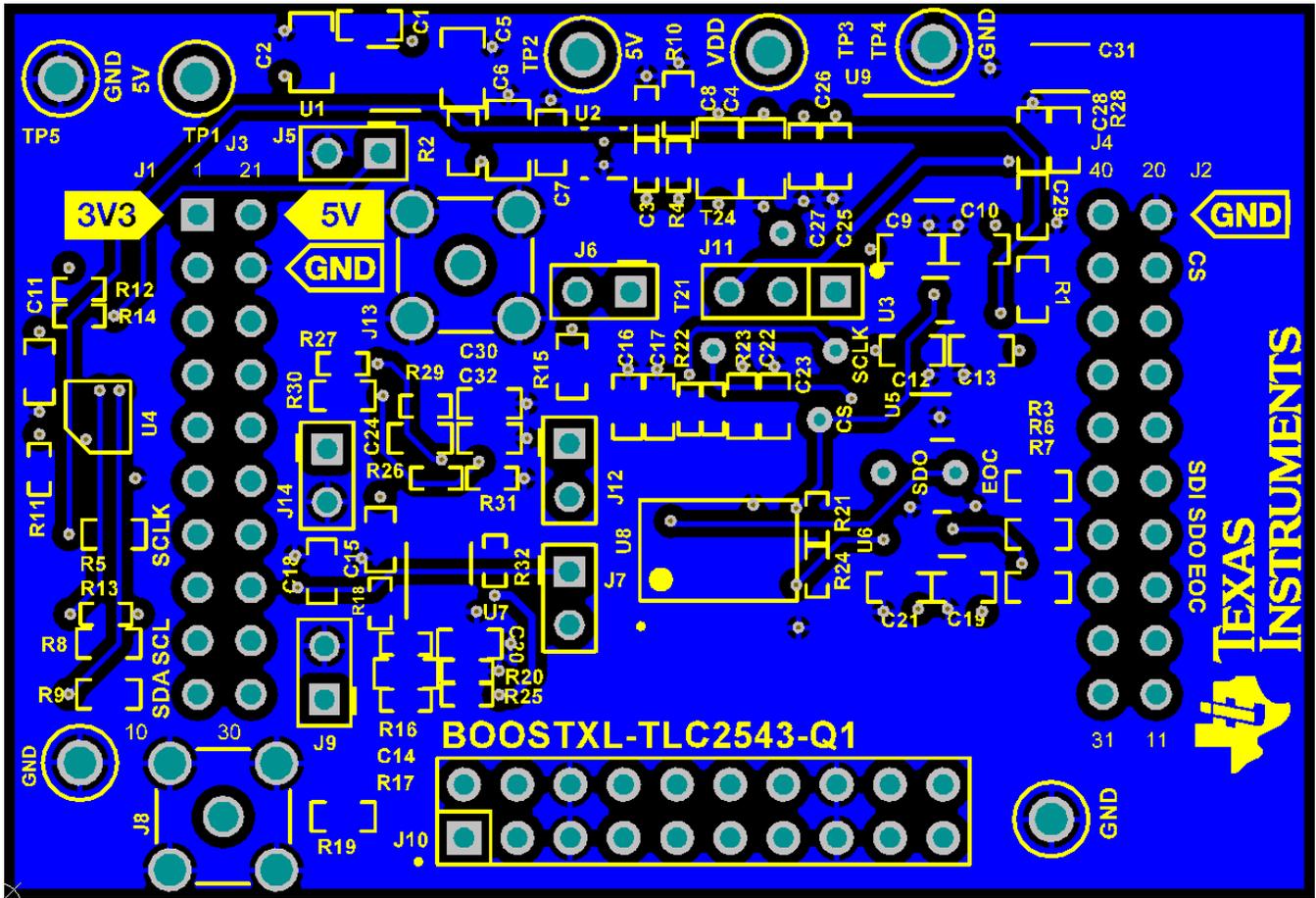


Figure 17. BOOSTXL-TLC2543 Bottom Layer Routing

### 5.3 Schematics

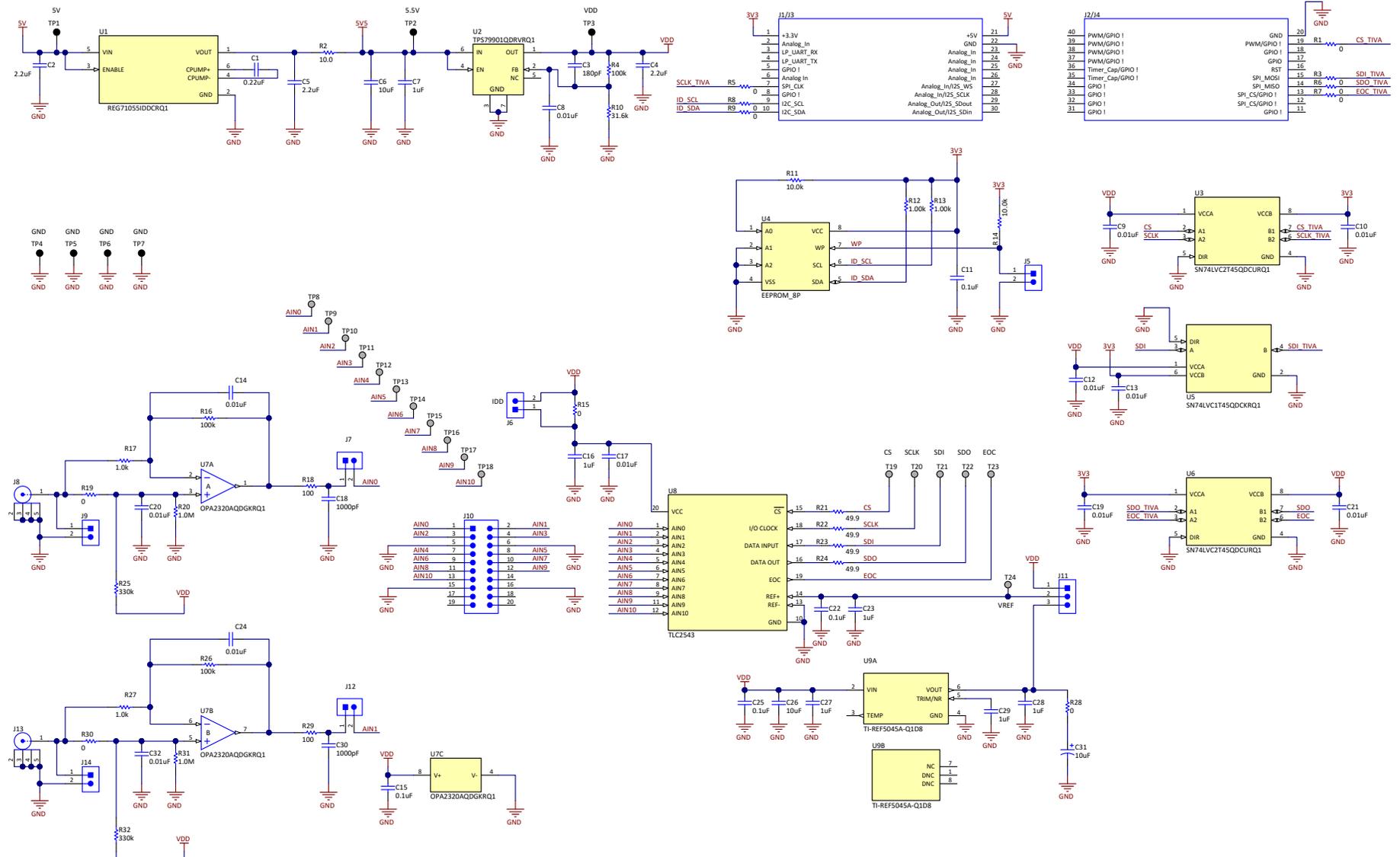


Figure 18. BOOSTXL-TLC2543 EVM Schematic Diagram

## STANDARD TERMS FOR EVALUATION MODULES

1. *Delivery:* TI delivers TI evaluation boards, kits, or modules, including any accompanying demonstration software, components, and/or documentation which may be provided together or separately (collectively, an "EVM" or "EVMs") to the User ("User") in accordance with the terms set forth herein. User's acceptance of the EVM is expressly subject to the following terms.
  - 1.1 EVMs are intended solely for product or software developers for use in a research and development setting to facilitate feasibility evaluation, experimentation, or scientific analysis of TI semiconductor products. EVMs have no direct function and are not finished products. EVMs shall not be directly or indirectly assembled as a part or subassembly in any finished product. For clarification, any software or software tools provided with the EVM ("Software") shall not be subject to the terms and conditions set forth herein but rather shall be subject to the applicable terms that accompany such Software
  - 1.2 EVMs are not intended for consumer or household use. EVMs may not be sold, sublicensed, leased, rented, loaned, assigned, or otherwise distributed for commercial purposes by Users, in whole or in part, or used in any finished product or production system.
2. *Limited Warranty and Related Remedies/Disclaimers:*
  - 2.1 These terms do not apply to Software. The warranty, if any, for Software is covered in the applicable Software License Agreement.
  - 2.2 TI warrants that the TI EVM will conform to TI's published specifications for ninety (90) days after the date TI delivers such EVM to User. Notwithstanding the foregoing, TI shall not be liable for a nonconforming EVM if (a) the nonconformity was caused by neglect, misuse or mistreatment by an entity other than TI, including improper installation or testing, or for any EVMs that have been altered or modified in any way by an entity other than TI, (b) the nonconformity resulted from User's design, specifications or instructions for such EVMs or improper system design, or (c) User has not paid on time. Testing and other quality control techniques are used to the extent TI deems necessary. TI does not test all parameters of each EVM. User's claims against TI under this Section 2 are void if User fails to notify TI of any apparent defects in the EVMs within ten (10) business days after delivery, or of any hidden defects with ten (10) business days after the defect has been detected.
  - 2.3 TI's sole liability shall be at its option to repair or replace EVMs that fail to conform to the warranty set forth above, or credit User's account for such EVM. TI's liability under this warranty shall be limited to EVMs that are returned during the warranty period to the address designated by TI and that are determined by TI not to conform to such warranty. If TI elects to repair or replace such EVM, TI shall have a reasonable time to repair such EVM or provide replacements. Repaired EVMs shall be warranted for the remainder of the original warranty period. Replaced EVMs shall be warranted for a new full ninety (90) day warranty period.
3. *Regulatory Notices:*
  - 3.1 *United States*
    - 3.1.1 *Notice applicable to EVMs not FCC-Approved:*

**FCC NOTICE:** This kit is designed to allow product developers to evaluate electronic components, circuitry, or software associated with the kit to determine whether to incorporate such items in a finished product and software developers to write software applications for use with the end product. This kit is not a finished product and when assembled may not be resold or otherwise marketed unless all required FCC equipment authorizations are first obtained. Operation is subject to the condition that this product not cause harmful interference to licensed radio stations and that this product accept harmful interference. Unless the assembled kit is designed to operate under part 15, part 18 or part 95 of this chapter, the operator of the kit must operate under the authority of an FCC license holder or must secure an experimental authorization under part 5 of this chapter.
    - 3.1.2 *For EVMs annotated as FCC – FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant:*

### CAUTION

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

### FCC Interference Statement for Class A EVM devices

*NOTE: This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.*

## FCC Interference Statement for Class B EVM devices

*NOTE: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:*

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

### 3.2 Canada

3.2.1 For EVMs issued with an Industry Canada Certificate of Conformance to RSS-210 or RSS-247

#### Concerning EVMs Including Radio Transmitters:

This device complies with Industry Canada license-exempt RSSs. Operation is subject to the following two conditions:

(1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

#### Concernant les EVMs avec appareils radio:

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes: (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

#### Concerning EVMs Including Detachable Antennas:

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication. This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

#### Concernant les EVMs avec antennes détachables

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante. Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

### 3.3 Japan

3.3.1 *Notice for EVMs delivered in Japan:* Please see [http://www.tij.co.jp/lstds/ti\\_ja/general/eStore/notice\\_01.page](http://www.tij.co.jp/lstds/ti_ja/general/eStore/notice_01.page) 日本国内に輸入される評価用キット、ボードについては、次のところをご覧ください。  
[http://www.tij.co.jp/lstds/ti\\_ja/general/eStore/notice\\_01.page](http://www.tij.co.jp/lstds/ti_ja/general/eStore/notice_01.page)

3.3.2 *Notice for Users of EVMs Considered "Radio Frequency Products" in Japan:* EVMs entering Japan may not be certified by TI as conforming to Technical Regulations of Radio Law of Japan.

If User uses EVMs in Japan, not certified to Technical Regulations of Radio Law of Japan, User is required to follow the instructions set forth by Radio Law of Japan, which includes, but is not limited to, the instructions below with respect to EVMs (which for the avoidance of doubt are stated strictly for convenience and should be verified by User):

1. Use EVMs in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry's Rule for Enforcement of Radio Law of Japan,
2. Use EVMs only after User obtains the license of Test Radio Station as provided in Radio Law of Japan with respect to EVMs, or
3. Use of EVMs only after User obtains the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to EVMs. Also, do not transfer EVMs, unless User gives the same notice above to the transferee. Please note that if User does not follow the instructions above, User will be subject to penalties of Radio Law of Japan.

【無線電波を送信する製品の開発キットをお使いになる際の注意事項】 開発キットの中には技術基準適合証明を受けていないものがあります。技術適合証明を受けていないものご使用に際しては、電波法遵守のため、以下のいずれかの措置を取っていただく必要がありますのでご注意ください。

1. 電波法施行規則第6条第1項第1号に基づく平成18年3月28日総務省告示第173号で定められた電波暗室等の試験設備でご使用いただく。
2. 実験局の免許を取得後ご使用いただく。
3. 技術基準適合証明を取得後ご使用いただく。

なお、本製品は、上記の「ご使用にあたっての注意」を譲渡先、移転先に通知しない限り、譲渡、移転できないものとします。

上記を遵守頂けない場合は、電波法の罰則が適用される可能性があることをご留意ください。日本テキサス・インスツルメンツ株式会社  
東京都新宿区西新宿 6 丁目 2 4 番 1 号  
西新宿三井ビル

3.3.3 *Notice for EVMs for Power Line Communication:* Please see [http://www.tij.co.jp/lstds/ti\\_ja/general/eStore/notice\\_02.page](http://www.tij.co.jp/lstds/ti_ja/general/eStore/notice_02.page)  
電力線搬送波通信についての開発キットをお使いになる際の注意事項については、次のところをご覧ください。 [http://www.tij.co.jp/lstds/ti\\_ja/general/eStore/notice\\_02.page](http://www.tij.co.jp/lstds/ti_ja/general/eStore/notice_02.page)

#### 3.4 *European Union*

##### 3.4.1 *For EVMs subject to EU Directive 2014/30/EU (Electromagnetic Compatibility Directive):*

This is a class A product intended for use in environments other than domestic environments that are connected to a low-voltage power-supply network that supplies buildings used for domestic purposes. In a domestic environment this product may cause radio interference in which case the user may be required to take adequate measures.

#### 4 *EVM Use Restrictions and Warnings:*

4.1 EVMS ARE NOT FOR USE IN FUNCTIONAL SAFETY AND/OR SAFETY CRITICAL EVALUATIONS, INCLUDING BUT NOT LIMITED TO EVALUATIONS OF LIFE SUPPORT APPLICATIONS.

4.2 User must read and apply the user guide and other available documentation provided by TI regarding the EVM prior to handling or using the EVM, including without limitation any warning or restriction notices. The notices contain important safety information related to, for example, temperatures and voltages.

##### 4.3 *Safety-Related Warnings and Restrictions:*

4.3.1 User shall operate the EVM within TI's recommended specifications and environmental considerations stated in the user guide, other available documentation provided by TI, and any other applicable requirements and employ reasonable and customary safeguards. Exceeding the specified performance ratings and specifications (including but not limited to input and output voltage, current, power, and environmental ranges) for the EVM may cause personal injury or death, or property damage. If there are questions concerning performance ratings and specifications, User should contact a TI field representative prior to connecting interface electronics including input power and intended loads. Any loads applied outside of the specified output range may also result in unintended and/or inaccurate operation and/or possible permanent damage to the EVM and/or interface electronics. Please consult the EVM user guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative. During normal operation, even with the inputs and outputs kept within the specified allowable ranges, some circuit components may have elevated case temperatures. These components include but are not limited to linear regulators, switching transistors, pass transistors, current sense resistors, and heat sinks, which can be identified using the information in the associated documentation. When working with the EVM, please be aware that the EVM may become very warm.

4.3.2 EVMs are intended solely for use by technically qualified, professional electronics experts who are familiar with the dangers and application risks associated with handling electrical mechanical components, systems, and subsystems. User assumes all responsibility and liability for proper and safe handling and use of the EVM by User or its employees, affiliates, contractors or designees. User assumes all responsibility and liability to ensure that any interfaces (electronic and/or mechanical) between the EVM and any human body are designed with suitable isolation and means to safely limit accessible leakage currents to minimize the risk of electrical shock hazard. User assumes all responsibility and liability for any improper or unsafe handling or use of the EVM by User or its employees, affiliates, contractors or designees.

4.4 User assumes all responsibility and liability to determine whether the EVM is subject to any applicable international, federal, state, or local laws and regulations related to User's handling and use of the EVM and, if applicable, User assumes all responsibility and liability for compliance in all respects with such laws and regulations. User assumes all responsibility and liability for proper disposal and recycling of the EVM consistent with all applicable international, federal, state, and local requirements.

5. *Accuracy of Information:* To the extent TI provides information on the availability and function of EVMs, TI attempts to be as accurate as possible. However, TI does not warrant the accuracy of EVM descriptions, EVM availability or other information on its websites as accurate, complete, reliable, current, or error-free.

6. *Disclaimers:*

6.1 EXCEPT AS SET FORTH ABOVE, EVMS AND ANY MATERIALS PROVIDED WITH THE EVM (INCLUDING, BUT NOT LIMITED TO, REFERENCE DESIGNS AND THE DESIGN OF THE EVM ITSELF) ARE PROVIDED "AS IS" AND "WITH ALL FAULTS." TI DISCLAIMS ALL OTHER WARRANTIES, EXPRESS OR IMPLIED, REGARDING SUCH ITEMS, INCLUDING BUT NOT LIMITED TO ANY EPIDEMIC FAILURE WARRANTY OR IMPLIED WARRANTIES OF MERCHANTABILITY OR FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF ANY THIRD PARTY PATENTS, COPYRIGHTS, TRADE SECRETS OR OTHER INTELLECTUAL PROPERTY RIGHTS.

6.2 EXCEPT FOR THE LIMITED RIGHT TO USE THE EVM SET FORTH HEREIN, NOTHING IN THESE TERMS SHALL BE CONSTRUED AS GRANTING OR CONFERRING ANY RIGHTS BY LICENSE, PATENT, OR ANY OTHER INDUSTRIAL OR INTELLECTUAL PROPERTY RIGHT OF TI, ITS SUPPLIERS/LICENSORS OR ANY OTHER THIRD PARTY, TO USE THE EVM IN ANY FINISHED END-USER OR READY-TO-USE FINAL PRODUCT, OR FOR ANY INVENTION, DISCOVERY OR IMPROVEMENT, REGARDLESS OF WHEN MADE, CONCEIVED OR ACQUIRED.

7. *USER'S INDEMNITY OBLIGATIONS AND REPRESENTATIONS.* USER WILL DEFEND, INDEMNIFY AND HOLD TI, ITS LICENSORS AND THEIR REPRESENTATIVES HARMLESS FROM AND AGAINST ANY AND ALL CLAIMS, DAMAGES, LOSSES, EXPENSES, COSTS AND LIABILITIES (COLLECTIVELY, "CLAIMS") ARISING OUT OF OR IN CONNECTION WITH ANY HANDLING OR USE OF THE EVM THAT IS NOT IN ACCORDANCE WITH THESE TERMS. THIS OBLIGATION SHALL APPLY WHETHER CLAIMS ARISE UNDER STATUTE, REGULATION, OR THE LAW OF TORT, CONTRACT OR ANY OTHER LEGAL THEORY, AND EVEN IF THE EVM FAILS TO PERFORM AS DESCRIBED OR EXPECTED.

8. *Limitations on Damages and Liability:*

8.1 *General Limitations.* IN NO EVENT SHALL TI BE LIABLE FOR ANY SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL, OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF THESE TERMS OR THE USE OF THE EVMS, REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES. EXCLUDED DAMAGES INCLUDE, BUT ARE NOT LIMITED TO, COST OF REMOVAL OR REINSTALLATION, ANCILLARY COSTS TO THE PROCUREMENT OF SUBSTITUTE GOODS OR SERVICES, RETESTING, OUTSIDE COMPUTER TIME, LABOR COSTS, LOSS OF GOODWILL, LOSS OF PROFITS, LOSS OF SAVINGS, LOSS OF USE, LOSS OF DATA, OR BUSINESS INTERRUPTION. NO CLAIM, SUIT OR ACTION SHALL BE BROUGHT AGAINST TI MORE THAN TWELVE (12) MONTHS AFTER THE EVENT THAT GAVE RISE TO THE CAUSE OF ACTION HAS OCCURRED.

8.2 *Specific Limitations.* IN NO EVENT SHALL TI'S AGGREGATE LIABILITY FROM ANY USE OF AN EVM PROVIDED HEREUNDER, INCLUDING FROM ANY WARRANTY, INDEMNITY OR OTHER OBLIGATION ARISING OUT OF OR IN CONNECTION WITH THESE TERMS, EXCEED THE TOTAL AMOUNT PAID TO TI BY USER FOR THE PARTICULAR EVM(S) AT ISSUE DURING THE PRIOR TWELVE (12) MONTHS WITH RESPECT TO WHICH LOSSES OR DAMAGES ARE CLAIMED. THE EXISTENCE OF MORE THAN ONE CLAIM SHALL NOT ENLARGE OR EXTEND THIS LIMIT.

9. *Return Policy.* Except as otherwise provided, TI does not offer any refunds, returns, or exchanges. Furthermore, no return of EVM(s) will be accepted if the package has been opened and no return of the EVM(s) will be accepted if they are damaged or otherwise not in a resalable condition. If User feels it has been incorrectly charged for the EVM(s) it ordered or that delivery violates the applicable order, User should contact TI. All refunds will be made in full within thirty (30) working days from the return of the components(s), excluding any postage or packaging costs.

10. *Governing Law:* These terms and conditions shall be governed by and interpreted in accordance with the laws of the State of Texas, without reference to conflict-of-laws principles. User agrees that non-exclusive jurisdiction for any dispute arising out of or relating to these terms and conditions lies within courts located in the State of Texas and consents to venue in Dallas County, Texas. Notwithstanding the foregoing, any judgment may be enforced in any United States or foreign court, and TI may seek injunctive relief in any United States or foreign court.

## IMPORTANT NOTICE FOR TI DESIGN INFORMATION AND RESOURCES

Texas Instruments Incorporated ("TI") technical, application or other design advice, services or information, including, but not limited to, reference designs and materials relating to evaluation modules, (collectively, "TI Resources") are intended to assist designers who are developing applications that incorporate TI products; by downloading, accessing or using any particular TI Resource in any way, you (individually or, if you are acting on behalf of a company, your company) agree to use it solely for this purpose and subject to the terms of this Notice.

TI's provision of TI Resources does not expand or otherwise alter TI's applicable published warranties or warranty disclaimers for TI products, and no additional obligations or liabilities arise from TI providing such TI Resources. TI reserves the right to make corrections, enhancements, improvements and other changes to its TI Resources.

You understand and agree that you remain responsible for using your independent analysis, evaluation and judgment in designing your applications and that you have full and exclusive responsibility to assure the safety of your applications and compliance of your applications (and of all TI products used in or for your applications) with all applicable regulations, laws and other applicable requirements. You represent that, with respect to your applications, you have all the necessary expertise to create and implement safeguards that (1) anticipate dangerous consequences of failures, (2) monitor failures and their consequences, and (3) lessen the likelihood of failures that might cause harm and take appropriate actions. You agree that prior to using or distributing any applications that include TI products, you will thoroughly test such applications and the functionality of such TI products as used in such applications. TI has not conducted any testing other than that specifically described in the published documentation for a particular TI Resource.

You are authorized to use, copy and modify any individual TI Resource only in connection with the development of applications that include the TI product(s) identified in such TI Resource. NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT OF TI OR ANY THIRD PARTY IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information regarding or referencing third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of TI Resources may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI RESOURCES ARE PROVIDED "AS IS" AND WITH ALL FAULTS. TI DISCLAIMS ALL OTHER WARRANTIES OR REPRESENTATIONS, EXPRESS OR IMPLIED, REGARDING TI RESOURCES OR USE THEREOF, INCLUDING BUT NOT LIMITED TO ACCURACY OR COMPLETENESS, TITLE, ANY EPIDEMIC FAILURE WARRANTY AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY YOU AGAINST ANY CLAIM, INCLUDING BUT NOT LIMITED TO ANY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON ANY COMBINATION OF PRODUCTS EVEN IF DESCRIBED IN TI RESOURCES OR OTHERWISE. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, DIRECT, SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF TI RESOURCES OR USE THEREOF, AND REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

You agree to fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of your non-compliance with the terms and provisions of this Notice.

This Notice applies to TI Resources. Additional terms apply to the use and purchase of certain types of materials, TI products and services. These include; without limitation, TI's standard terms for semiconductor products (<http://www.ti.com/sc/docs/stdterms.htm>), [evaluation modules](#), and [samples](http://www.ti.com/sc/docs/sampterm.htm) (<http://www.ti.com/sc/docs/sampterm.htm>).

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
Copyright © 2018, Texas Instruments Incorporated